

银包铜粉 Silver-Coated Copper Powder

应用范围 (Application)

用于制备导电浆料、导电印刷油墨、导电胶、薄膜开关等中低温料浆，可以代替银粉用于电子行业上。

Apply to manufacture conducting paste, conducting printing ink, conducting resin, membrane switch and other intermediate and low-temperature paste, which can take the place of silver powder used in electronic industry.

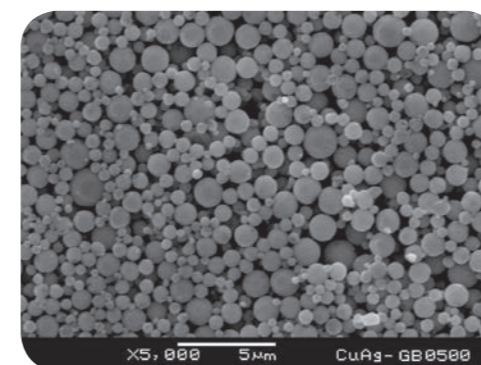
产品特性 (Features)

- ④ 粒径均匀 Uniform particle size
- ④ 分散性好 Good dispersion property
- ④ 抗氧化性好 Good oxidation resistance
- ④ 导电性好 Good electric conductivity

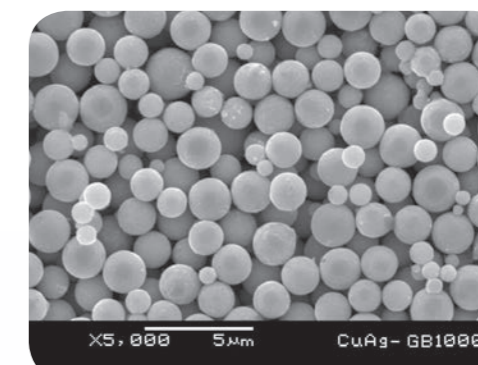
产品规格 (Product specification)

规格 Specification	平均粒径 Mean Particle Size (μm)	比表面积 Specific Surface Area (m^2/g)	粒度分布 Particle Size Distribution (μm)			银含量 Ag Content (wt%)
			D10	D50	D90	
CuAg-GB0500	0.50	1.05-1.70	≤ 2.80	≤ 4.50	≤ 6.50	15-50
CuAg-GB1000	1.00	0.50-1.00	≤ 3.30	≤ 5.50	≤ 9.50	10-30
CuAgF-GB1000	-	0.70-1.20	≤ 4.00	≤ 6.50	≤ 10.50	10-40

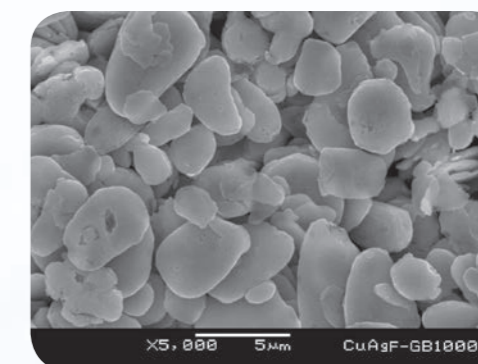
SEM 照片 (SEM photographs)



CuAg-GB0500



CuAg-GB1000



CuAgF-GB1000

可根据客户的要求提供不同的产品。

Products customized available.